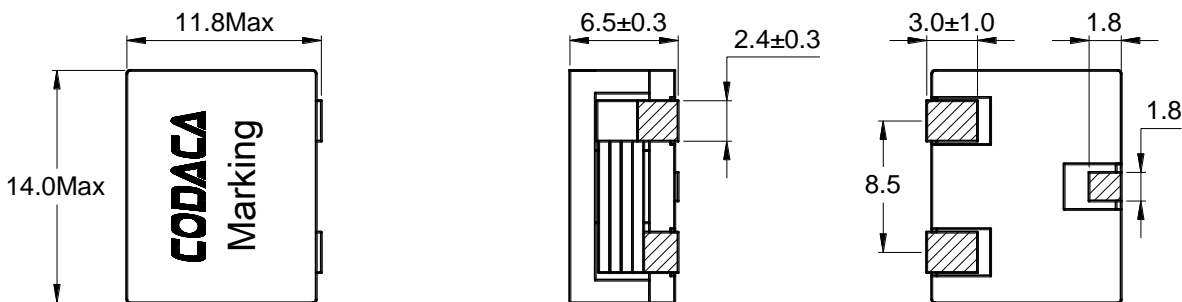


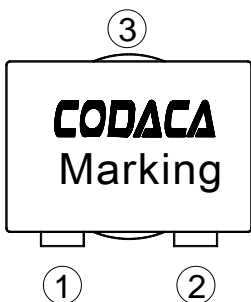
## Outline: 产品概要

- Magnetic shielding structure, excellent resistance to electro magnetic interference.  
磁屏蔽结构，抗电磁干扰(EMI)性能强。
- Assemblage design, sturdy structure.  
组立式设计，结构坚固。
- Small volume, high current, low magnetic loss, low ESR, small parasitic capacitance.  
小体积，大电流，低磁损，低阻抗，寄生电容小。
- Temperature rise current and saturation current is less influenced by environment.  
温升电流及饱和电流受环境条件影响小。
- Operating temperature :  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$   
(Including coil's temperature rise)  
工作温度:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  (包含线圈发热)

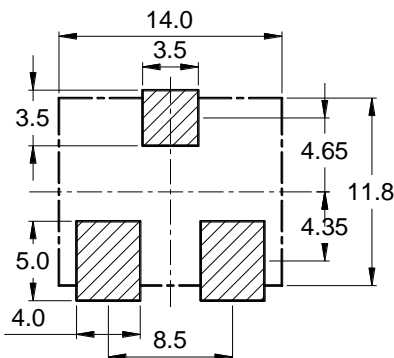
## 1 Appearance and dimensions (mm) 外形尺寸



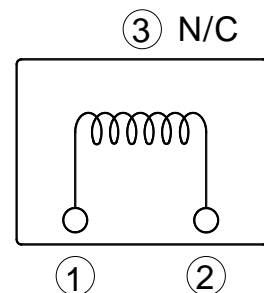
## 2 Marking 印字标识



## 3 Reference land pattern (mm) 参考基板尺寸



## 4 Schematic 原理图



## 5 Electrical characteristics

### 电气特性

| Part No.<br>型号 | Inductance ( $\mu\text{H}$ )<br>电感值 ※1<br>$\pm 20\%$ | D.C.R. ( $\text{m}\Omega$ )<br>直流电阻 |      | Saturation current (A)<br>饱和电流 ※2<br>Typical | Temperature rise current (A)<br>温升电流 ※3<br>Typical |
|----------------|--|-------------------------------------|------|--|--|
|                |  | Typical                             | Max  |  |  |
| CSCG1365-1R0M  | 1.00   | 2.00                                | 2.50 | 50.0   | 25.0   |

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.

电感测试条件为 100kHz, 0.1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.

饱和电流: 电感值下降其初始值的 20% 时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is  $\Delta T 40^\circ\text{C}$  ( $T_a = 25^\circ\text{C}$ ).

温升电流: 使产品温度上升到  $\Delta T 40^\circ\text{C}$  时所加载的实际直流电流值 ( $T_a = 25^\circ\text{C}$ )。

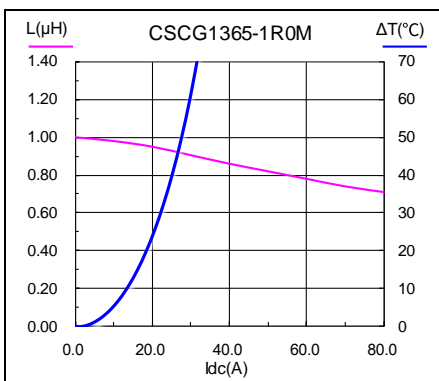
※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。

## 6 Saturation current VS temperature rise current curve

### 饱和电流 VS 温升电流曲线

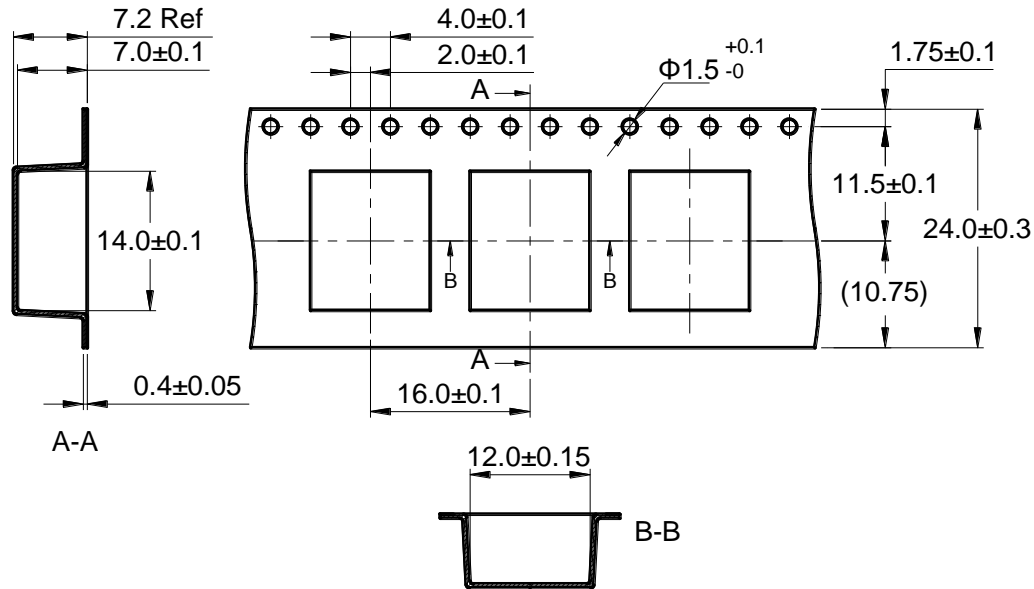


## 7 Packing specification

### 包装规格

#### 7.1 Carrier tape dimensions (mm)

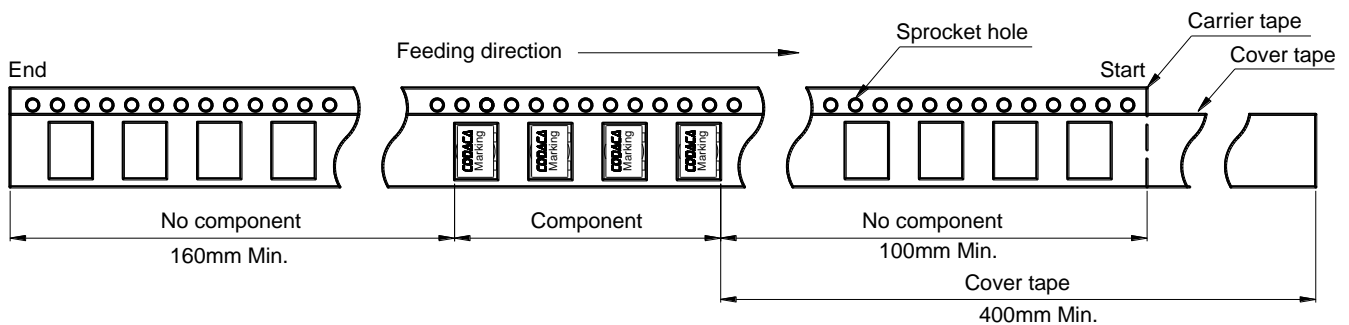
##### 载带尺寸



※ Packing is referred to the international standard IEC 60286-3.  
包装参照国际标准 IEC 60286-3。

#### 7.2 Tape direction

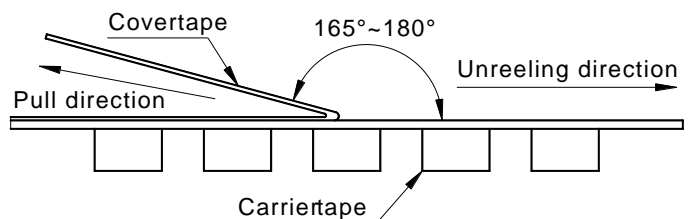
##### 捆包方向



#### 7.3 Cover tape peel off condition

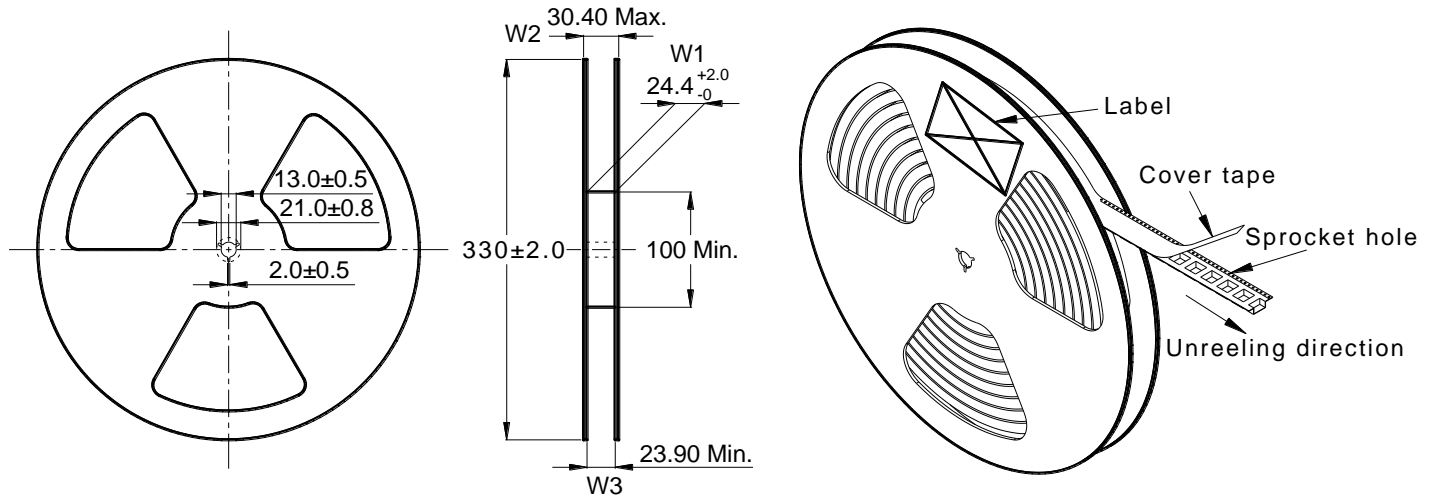
##### 盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.  
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.  
参考剥离速度 300±10mm/分钟。



## 7.4 Reel dimensions (mm)

卷盘尺寸



## 7.5 Carton dimensions and packing quantity

包装箱尺寸和包装数量

■ Inner Carton: 340×340×95mm  
内包装盒

■ Out Carton : 355×355×385mm  
外包装箱

| Product Series<br>产品系列 | Quantity / Reel<br>数量 / 卷 | Inner Carton Quantity<br>内盒 包装数量 | Out Carton Quantity<br>外箱 包装总数量 |
|------------------------|---------------------------|----------------------------------|---------------------------------|
| CSCG1365               | 400pcs                    | (400×2) = 800pcs                 | (800×3) = 2400pcs               |

## 7.6 Label making

标签标识

The following items will be marked on the reel of product label and shipping label.  
以下项目将明确标识于产品卷盘标签以及运输标签上。

| Production Label<br>产品标签           |
|------------------------------------|
| ■ Part No.<br>产品型号                 |
| ■ Electrical Information<br>产品电性信息 |
| ■ Quantity<br>数量                   |
| ■ Packing No.<br>包装流水号             |

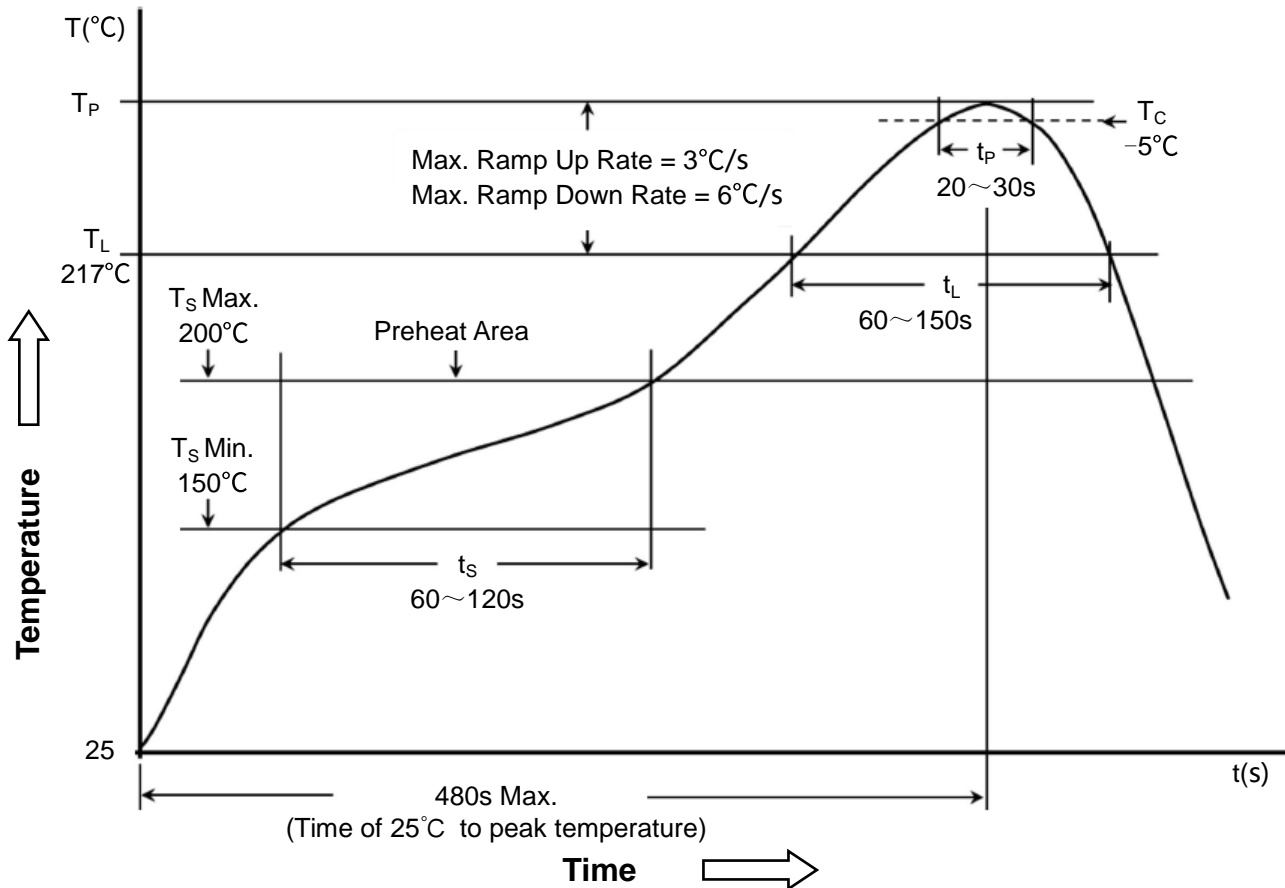
| Shipping Label<br>运输标签       |
|------------------------------|
| ■ Customer Name<br>客户名称      |
| ■ Customer Part No.<br>客户型号  |
| ■ Supplier Part No.<br>供应商型号 |
| ■ Supplier Name<br>供应商名称     |
| ■ Country of origin<br>产品产地  |

## 8 Soldering specification

### 焊接规格

#### 8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



#### 8.2 Classification of peak package body temperature (T<sub>P</sub>)

封装体峰值温度(T<sub>P</sub>)分类

|                          | Package Thickness<br>封装厚度 | Package Volume<br>封装体积 |                          |                       |
|--------------------------|---------------------------|------------------------|--------------------------|-----------------------|
|                          |                           | <350 mm <sup>3</sup>   | 350~2000 mm <sup>3</sup> | >2000 mm <sup>3</sup> |
| PB-Free Assembly<br>无铅装配 | <1.6mm                    | 260°C                  | 260°C                    | 260°C                 |
|                          | 1.6~2.5mm                 | 260°C                  | 250°C                    | 245°C                 |
|                          | ≥2.5mm                    | 250°C                  | 245°C                    | 245°C                 |

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.  
回流焊参照标准 IPC/JEDEC J-STD-020D.